

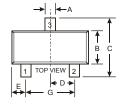
BAS21/A/C/S

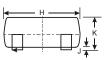
SURFACE MOUNT FAST SWITCHING DIODES

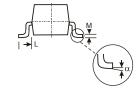
Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance

DEVICE	MARKING	TYPE	
BAS21	JS	Single	
BAS21A	JS2	Dual	
BAS21C	JS3	Dual	
BAS21S	JS4	Dual	







SOT-23				
Dim	Min	Max		
Α	0.37	0.51		
В	1.20	1.40		
С	2.30	2.50		
D	0.89	1.03		
E	0.45	0.60		
G	1.78	2.05		
Н	2.80	3.00		
J	0.013	0.10		
K	0.903	1.10		
L	0.45	0.61		
М	0.085	0.180		
α	0°	8°		
All Dimensions in mm				

Maximum Ratings @ TA = 25°C unless otherwise specified

	Parameter	Symbol	Limits	Unit
Repetitive Peak reverse voltage		V_{RRM}		
Working Peak reverse voltage DC		V_{RWM}	250	V
Blocking Voltage		V _R		
Forward Continuous Cu	rrent	I _{FM}	400	mA
Average Rectified Outpu	ut Current	Io	200	mA
Non-Repetitive Peak	@ t = 1.0μs		2.5	А
Forward Surge Current	@ t = 1.0s	I _{FSM}	0.5	
Repetitive Peak Forward	l Surge Current	I _{FRM}	625	mA
Power Dissipation		PD	250	mW
Thermal Resistance Junction to Ambient Air		R _{θJA}	500	°C/W
Junction temperature		TJ	150	°C
Storage temperature rar	nge	T _{STG}	-65-150	$^{\circ}$









Electrical Characteristics @ TA = 25°C unless otherwise specified

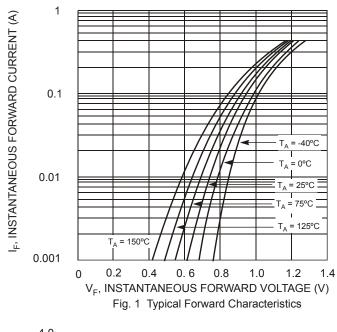
Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse breakdown voltage	V(BR)	IR= 100μA	250		V
Reverse voltage leakage current	IR	VR=200V		1	μA
Forward voltage	VF	IF=100mA IF=200mA		1000 1250	mV
Diode capacitance	CD	VR=0V, f=1MHz		5	pF
Reveres recovery time	trr	IF=IR=30mA,Irr=0.1×IR,RL=100Ω		50	nS

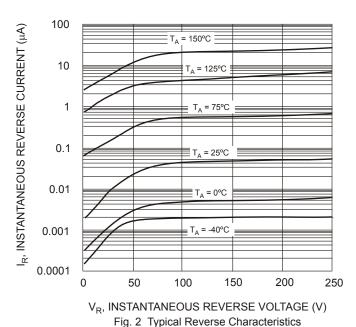


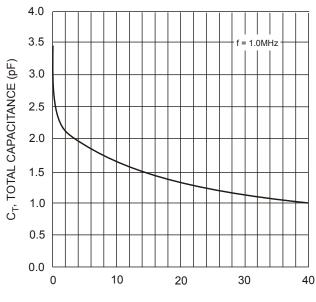
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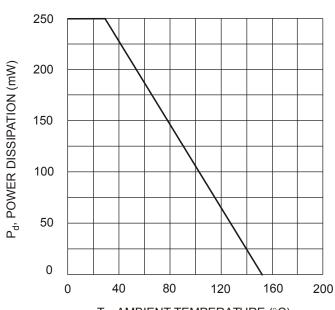
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TYPICAL TRANSIENT CHARACTERISTICS









 V_R , REVERSE VOLTAGE (V) Fig. 3 Typical Capacitance vs. Reverse Voltage

T_A, AMBIENT TEMPERATURE (°C)
Fig. 4 Power Derating Curve, Total Package

http://www.hc-semi.com



BAS21/A/C/S

SURFACE MOUNT FAST SWITCHING DIODES

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